MSP 3000 MICROSENS

CHASSIS OVERVIEW

The MSP 3000 platform consists of four rack mountable chassis types that were engineered to deliver maximum capacity (scales to over 8Tbps) while requiring minimum space and power. The chassis share both a single software and wide variety of pluggable modules, which allows you to optimize a solution for your specific network needs. The system consists of a 7RU chassis for high density hub and aggregation applications, and multiple 2RU chassis for applications where space and power are key considerations. The system supports both DWDM and CWDM and includes optical multiplexers (Mux/Demux), reconfigurable optical add/drop multiplexers (ROADM) and optical amplifiers (OA). Mux and Demux filter modules are designed in a modular fashion to accommodate channel growth without service interruption.

| FEATURES | MS430504M | MS430501M | MS430503M | MS430501MX |
|----------------------------------|----------------------------------|----------------------------------|----------------------------------|----------------------------------|
| Rack Unit | 7RU | 2RU | 2RU | 2RU |
| Height | 311 mm | 87 mm | 87 mm | 87 mm |
| Width | 442 mm | 442 mm | 442 mm | 442 mm |
| Depth | 264 mm | 240 mm | 413 mm | 240 mm |
| Typical Power | 76 W | 120 W | 120 W | 120 W |
| Max Power | 1000 W | 500 W | 500 W | 500 W |
| Fuse Raiting | 40 Amp | 20 Amp | 20 Amp | 20 Amp |
| Power Voltage | -48 VDC | -48 VDC | 230 VAC | 24 VDC |
| DC Power | Dual, redundant, load sharing | Dual, redundant, load sharing | Dual, redundant, load sharing | Dual, redundant, load sharing |
| AC Power | External | External | Internal | External |
| Mounting | ETSI, 19" and 23" |
| Operating Temp | 0 +50°C | 0 +50°C | 0 +50°C | 0 +50°C |
| MGNT | MS430520M-B | MS430520M-B | MS430520M-B | MS430520MX-B |
| Slot Count | 20 + 1MGNT | 6 + 1MGNT | 6 + 1MGNT | 6 + 1MGNT |
| Repleacable FAN & Dust Filter | Yes | Yes | Yes | Yes |

| Order Infor | mation | |
|--------------------|--|--|
| Article no. | Description | |
| MS430503M | MSP3200 - 19" Chassis 2 HU, 6 module slots, 2x 230 VAC power input, incl. Backplane | |
| MS430501M | MSP3200 - 19" Chassis 2 HU, 6 module slots, 2x 48 VDC power input, incl. Backplane | |
| MS430504M | MSP3700 - 19" Chassis 7 HU, 20 module slots, 2x 48 VDC power input, incl. Backplane | |
| MS430501MX | MSP3200 - 19" Chassis 2 HU, 6 module slots, 2x 24 VDC power input, incl. Backplane, extended Temperature Range | |
| • | | |

MICROSENS reserves the right to make any changes without further notice to any product to improve reliability, function or design. MICROSENS does not assume any liability arising out of the application or use of any product. pp/0818